# PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE:      | NEW ASSIGNMENT |  |
|-----------------------|----------------|--|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |  |

## **CONVEYING PARTY DATA**

| Name             | Execution Date |  |
|------------------|----------------|--|
| Chien Ling HWANG | 05/20/2010     |  |
| Hui-Jung TSAI    | 05/20/2010     |  |
| Yi-Wen WU        | 05/02/2010     |  |
| Chung-Shi LIU    | 05/20/2010     |  |

#### RECEIVING PARTY DATA

| Name:           | TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. |
|-----------------|--------------------------------------------------|
| Street Address: | No. 8, Li-Hsin Rd. VI, Hsinchu Science Park      |
| City:           | Hsinchu                                          |
| State/Country:  | TAIWAN                                           |
| Postal Code:    | 300                                              |

## PROPERTY NUMBERS Total: 1

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 12792002 |

### **CORRESPONDENCE DATA**

Fax Number: (703)518-5499

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 7036841111

Email: sramunto@ipfirm.com

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER: T5057-B247

NAME OF SUBMITTER: Benjamin J. Hauptman

Total Attachments: 1

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OP \$40,00 1279200

501192466 REEL: 024470 FRAME: 0343

Docket No. T5057-B247

## ASSIGNMENT

| In consideration of the premises and         | other good and | l valuable consideration | n in hand pai | d, the receipt and | l sufficiency of |
|----------------------------------------------|----------------|--------------------------|---------------|--------------------|------------------|
| which is hereby acknowledged, the undersigne | :d,            |                          |               |                    |                  |

- 1) Chien Ling HWANG
- 4) Chung-Shi LIU

- 2) Hui-Jung TSAI
- 3) Yi-Wen WU

RECORDED: 06/02/2010

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

# TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

### 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

#### CU PILLAR BUMP WITH NON-METAL SIDEWALL SPACER AND METAL TOP CAP

- and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or

all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chia Ling twang
Name: Chien Ling HWANG

Date:

2) Hui - Jung Isai
Name: Hui-Jung TSAI

Date:

3) Li - Wen WU

Name: Yi-Wen WU

Name: Chung-Shi LIU

Date:

PATENT REEL: 024470 FRAME: 0344